

RoHS Compliant Product  
A suffix of "-C" specifies halogen & lead-free

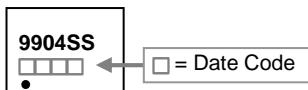
## DESCRIPTION

The SSG9904 provide the designer with the best Combination of fast switching, ruggedized device design, Ultra low on-resistance and cost-effectiveness.

## FEATURES

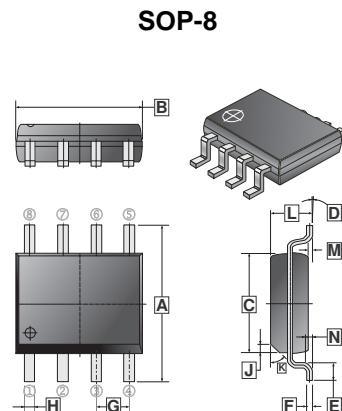
- Low on-resistance
- Simple Drive Requirement
- Double-N MosFET Package

## MARKING CODE

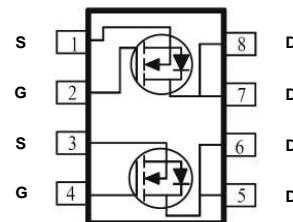


## PACKAGE INFORMATION

Package	MPQ	Leader Size
SOP-8	3K	13' inch



REF.	Millimeter Min.	Millimeter Max.	REF.	Millimeter Min.	Millimeter Max.
A	5.80	6.20	H	0.35	0.49
B	4.80	5.00	J	0.375	REF.
C	3.80	4.00	K	45°	
D	0°	8°	L	1.35	1.75
E	0.40	0.90	M	0.10	0.25
F	0.19	0.25	N	0.25	REF.
G	1.27 TYP.				



## ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	$V_{DS}$	40	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current@ $V_{GS} = 10\text{V}$ <sup>1</sup>	$I_D$	7.2	A
		5.6	
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	14.5	A
Single Pulse Avalanche Energy <sup>3</sup>	$E_{AS}$	28	mJ
Avalanche Current	$I_{AS}$	17.8	A
Power Dissipation@ $T_C=25^\circ\text{C}$ <sup>4</sup>	$P_D$	2.5	W
Operating Junction & Storage Temperature Range	$T_J, T_{STG}$	-55~150	°C
Thermal Resistance Ratings			
Thermal Resistance Junction-ambient (Max.) <sup>1</sup>	$R_{\theta JA}$	85	°C / W
Thermal Resistance Junction-Case (Max.) <sup>1</sup>	$R_{\theta JC}$	50	°C / W

**ELECTRICAL CHARACTERISTICS** ( $T_j = 25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
<b>Static</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	40	-	-	V	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$
Breakdown Voltage Temp. Coefficient	$\Delta BV_{DS}/\Delta T_j$	-	0.034	-	V / $^\circ\text{C}$	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$
Gate-Threshold Voltage	$V_{GS(th)}$	1	-	2.5	V	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$
Forward Transconductance	$G_{fs}$	-	14	-	S	$V_{DS}=5\text{V}, I_D=6\text{A}$
Gate-Body Leakage	$I_{GSS}$	-	-	$\pm 100$	nA	$V_{GS}=\pm 20\text{V}$
Zero Gate Voltage Drain Current	$I_{DSS}$	-	-	1	$\mu\text{A}$	$V_{DS}=32\text{V}, V_{GS}=0, T_j=25^\circ\text{C}$
		-	-	5		$V_{DS}=32\text{V}, V_{GS}=0, T_j=55^\circ\text{C}$
Drain-Source On-Resistance <sup>2</sup>	$R_{DS(ON)}$	-	-	26	$\text{m}\Omega$	$V_{GS}=10\text{V}, I_D=6\text{A}$
		-	-	35		$V_{GS}=4.5\text{V}, I_D=4\text{A}$
Total Gate Charge	$Q_g$	-	5.5	-	nC	$I_D=6\text{A}$ $V_{DS}=20\text{V}$ $V_{GS}=4.5\text{V}$
Gate-Source Charge	$Q_{gs}$	-	1.25	-		
Gate-Drain ("Miller") Charge	$Q_{gd}$	-	2.5	-		
Turn-On Delay Time	$T_{d(on)}$	-	8.9	-	nS	$V_{DS}=20\text{V}$ $I_D=1\text{A}$ $V_{GS}=10\text{V}$ $R_G=3.3\Omega$ $R_D=20\Omega$
Rise Time	$T_r$	-	2.2	-		
Turn-Off Delay Time	$T_{d(off)}$	-	41	-		
Fall Time	$T_f$	-	2.7	-		
Input Capacitance	$C_{iss}$	-	593	-	pF	$V_{GS}=0\text{V}$ $V_{DS}=15\text{V}$ $f=1.0\text{MHz}$
Output Capacitance	$C_{oss}$	-	76	-		
Reverse Transfer Capacitance	$C_{rss}$	-	56	-		
<b>Guaranteed Avalanche Characteristics</b>						
Single Pulse Avalanche Energy <sup>5</sup>	EAS	9	-	-	mJ	$V_{DD}=25\text{V}, L=0.1\text{mH}, I_{AS}=10\text{A}$
<b>Source-Drain Diode</b>						
Forward On Voltage <sup>2</sup>	$V_{DS}$	-	-	1.2	V	$I_S=1\text{A}, V_{GS}=0\text{V}$
Continuous Source Current <sub>1,6</sub>	$I_S$	-	7.2	-	A	$V_{GS} = V_{DS}=0\text{V}$ , Force Current
Pulsed Source Current <sub>2,6</sub>	$I_{SM}$	-	14.5	-	A	

Notes:

1. Surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.  $135^\circ\text{C}/\text{W}$  when mounted on Min. copper pad.
2. The data tested by pulsed, pulse width  $\leq 300\text{us}$ , duty cycle  $\leq 2\%$ .
3. The EAS data shows Max. rating. The test condition is  $VDD=25\text{V}, VGS=10\text{V}, L=0.1\text{mH}, IAS=17.8\text{A}$ .
4. The power dissipation is limited by  $150^\circ\text{C}$  junction temperature.
5. The Min. value is 100% EAS tested guarantee.
6. The data is theoretically the same as ID and IDM, in real applications, should be limited by total power dissipation.

## CHARACTERISTICS CURVE

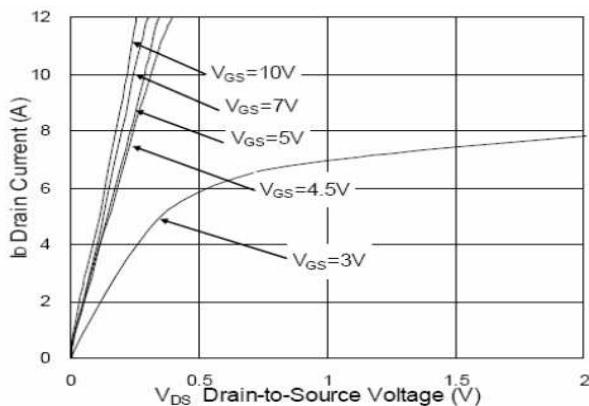


Fig.1 Typical Output Characteristics

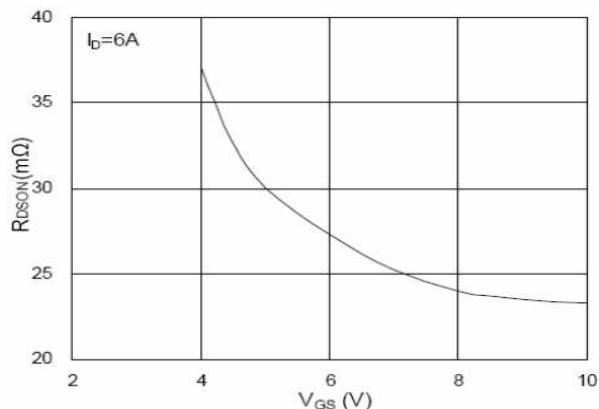


Fig.2 On-Resistance vs. G-S Voltage

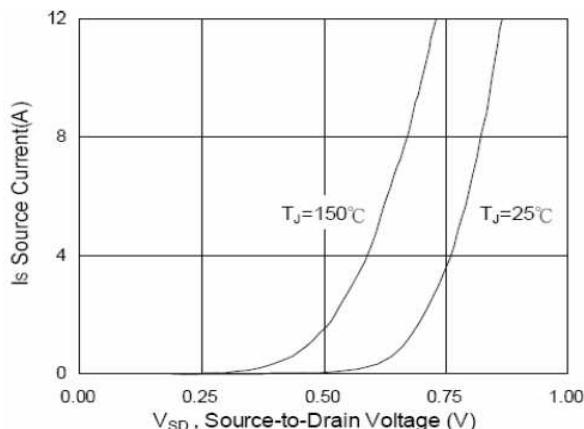


Fig.3 Forward Characteristics of Reverse

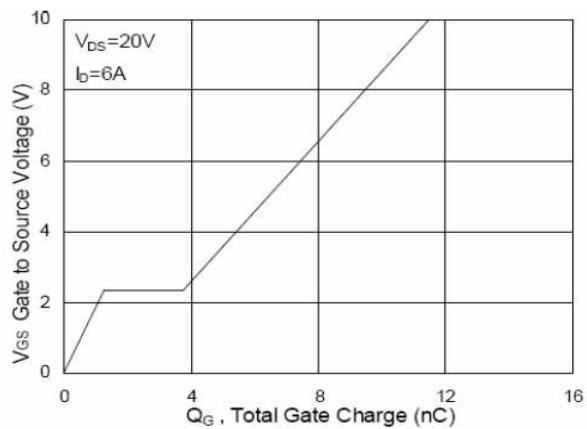


Fig.4 Gate-Charge Characteristics

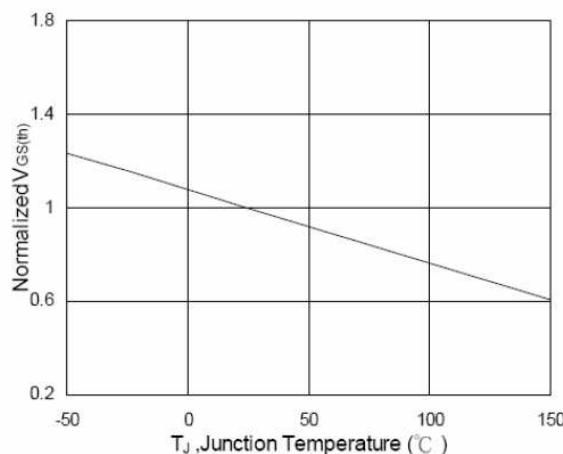


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$

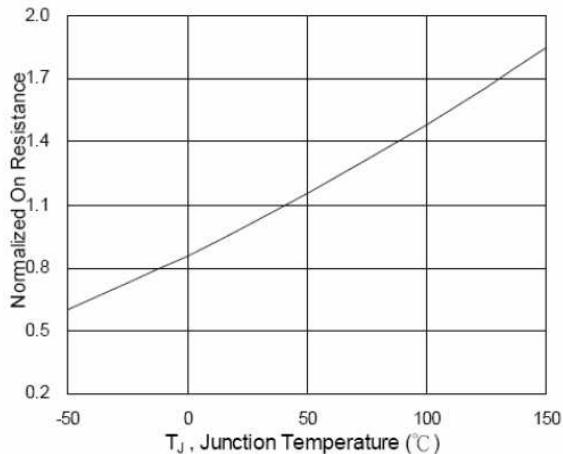


Fig.6 Normalized  $R_{DS(ON)}$  vs.  $T_J$

## CHARACTERISTICS CURVE

